



Synthesis of large-scale 2-D MoS₂ atomic layers by hydrogen-free and promoter-free chemical vapor deposition



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ABSTRACT

As one of the two-dimensional (2-D) transition metal dichalcogenides, atomically thin molybdenum disulfide (MoS₂) has attracted significant attention and research interests for micro and nanoelectronic applications. Significant efforts have been made to develop different approaches in order to obtain atomic layer MoS₂, such as exfoliation, chemical synthesis, and physical or chemical vapor deposition (CVD) processes. In this paper, we report a hydrogen-free and promoter-free CVD growth to synthesize large-area MoS₂ atomic layers. A variety of techniques including optical microscopy (OM), atomic force microscopy (AFM), photoluminescence (PL) mapping, Raman and x-ray photoelectron spectroscopy (XPS), high resolution electron microscopy (HREM) and scanning transmission electron microscopy (STEM) were applied to characterize the film quality, uniformity and layer numbers. High quality centimeter-sized MoS₂ atomic layers were demonstrated, which form a foundation to develop wafer-sized material platform for device fabrication and production.

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1. Introduction

Atomically thin MoS₂, as one of the prototypes of 2-D transition metal dichalcogenides (TMDs), has demonstrated desirable material properties for low power electronics and optoelectronic applications. These properties include large direct bandgap energy for monolayers [1,2], high carrier mobility [3], excellent current on/off ratio [4], high mechanical strength [5] and flexibility [6], etc. Considerable research efforts and investigation have been motivated to develop techniques to produce MoS₂ atomic layers. These techniques include various exfoliation processes [7–10], physical vapor deposition (PVD) [11–13], and chemical vapor deposition (CVD). For example, direct sulfurization of pre-deposited molybdenum thin film [14] or molybdenum trioxide (MoO₃) powder with graphene-like promoters [15] were reported, with MoS₂ crystal shapes investigated under different growth conditions [16]. A two-step thermal process [17] to convert MoO₃ to MoS₂ by hydrogen annealing and sulfurization have been demonstrated. A

self-limiting CVD approach [18] to grow MoS₂ films with layer numbers precisely controlled over an area of centimeters was also developed by sulfurization of MoCl₅. And another layer control approach for large-area MoS₂ film was proposed by treatment of the substrate surface with oxygen plasma [19]. Process using magnetron sputtering [20] was also developed to grow MoS₂ films by sputtering Mo metal target in vaporized sulfur ambient atomic high temperatures (> 700 °C). In summary, the goal of all these processes is to grow high quality large-area MoS₂ film, which is required for large-scale production of practical devices.

In this paper, we report a CVD synthesis method, hydrogen-free and promoter-free, for MoS₂ film growth on SiO₂/Si substrate. The film thickness, crystalline quality and layer numbers were characterized comprehensively by a variety of spectroscopic and microscopic techniques including OM, AFM, PL, Raman, XPS, HREM and STEM. Our results show that large-area MoS₂ atomic films were attainable with high quality as by other growth techniques, which is favorable for device applications.

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2. Experimental

Prior to the CVD process, the SiO₂/Si substrate (SiO₂ thickness: 280 nm) was cleaned with acetone, Isopropyl Alcohol (IPA) and deionized (DI) water, followed by piranha solution (H₂SO₄:

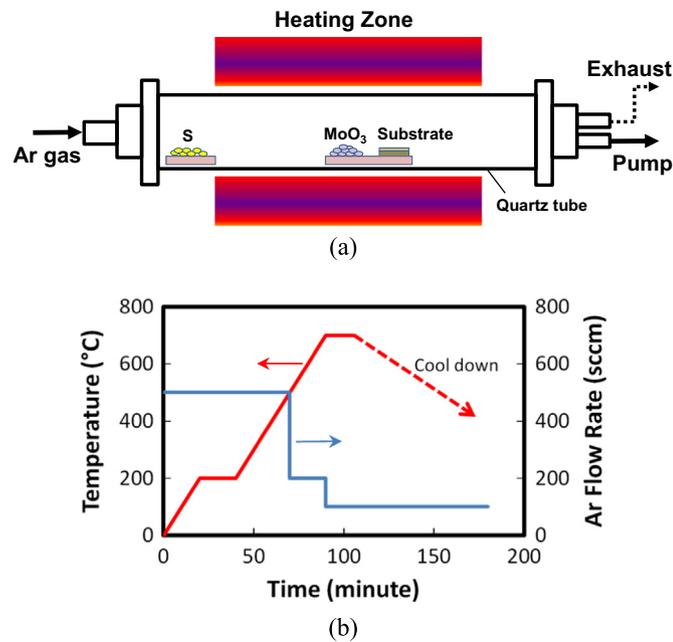


Fig. 1. (a) Schematic diagram of the CVD system for MoS₂ atomic layer growth; (b) temperature and gas flow programming during the chemical synthesis.

H₂O₂=1:1) and rinse thoroughly by DI water again. After dried completely, the substrate was loaded in a 2-inch-diameter quartz tube furnace. Fig. 1(a) illustrates the CVD setup for MoS₂ growth. Solid powders of MoO₃ (99.995%, 50 mg) and S (99.999%, 50 mg) were used as the precursor materials, and high purity argon (Ar) as the carrier gas. An alumina boat was used to contain S and placed upstream relative to the Ar gas flow direction, while another boat containing MoO₃ was placed close to the center of the heating zone. At room temperature, the quartz tube was first pumped down to remove the oxygen, followed by constant Ar gas flow started with a 500 sccm rate. While the furnace was heated up with a heating rate of 10 °C/min, the Ar gas flow was adjusted as shown in Fig. 1(b) to 100 sccm when temperature reached 700 °C. The precursor MoO₃ and S reacted at 700 °C for 15 min to produce MoS₂ species which precipitated onto the SiO₂/Si substrate to form MoS₂ thin film. After chemical synthesis, the furnace tube was cooled down to room temperature to unload the substrate.

3. Results and discussion

Optical characterizations of synthesized MoS₂ atomic film on the SiO₂/Si substrate are shown in Fig. 2. Photograph in Fig. 2 (a) displays the color of the as-grown MoS₂ under white light. Color contrast clearly shows areas of MoS₂ and SiO₂. Magnified image of MoS₂ film taken under optical microscope is illustrated in Fig. 2(b). It can be seen that the film is uniform and continuous across a large area without grain boundary. The thickness of the MoS₂ film was measured by AFM. Fig. 2(c) shows a typical AFM image of triangle-shaped MoS₂ crystals with clear grain boundaries attained by our CVD growth. Such triangle shape was also

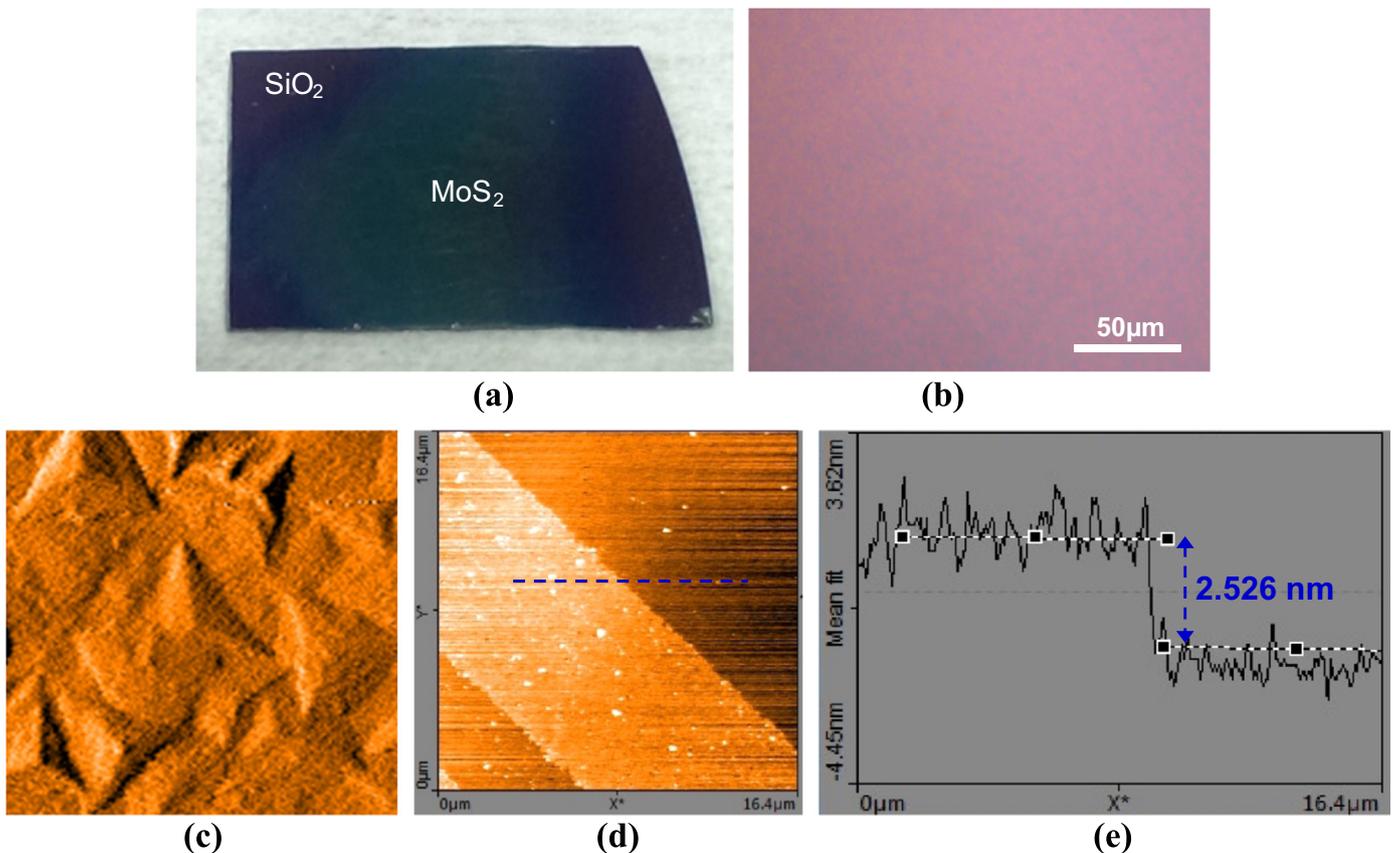


Fig. 2. Synthesized MoS₂ film on a SiO₂/Si substrate with (a) optical photograph with clear color contrast between MoS₂ and SiO₂, (b) microscopic image of MoS₂ film, and AFM images of MoS₂ crystals (c) in triangle shape before growth improvement, (d) forming a continuous film after improvement of growth parameters, and (e) thickness profile of a tri-layer MoS₂ film.

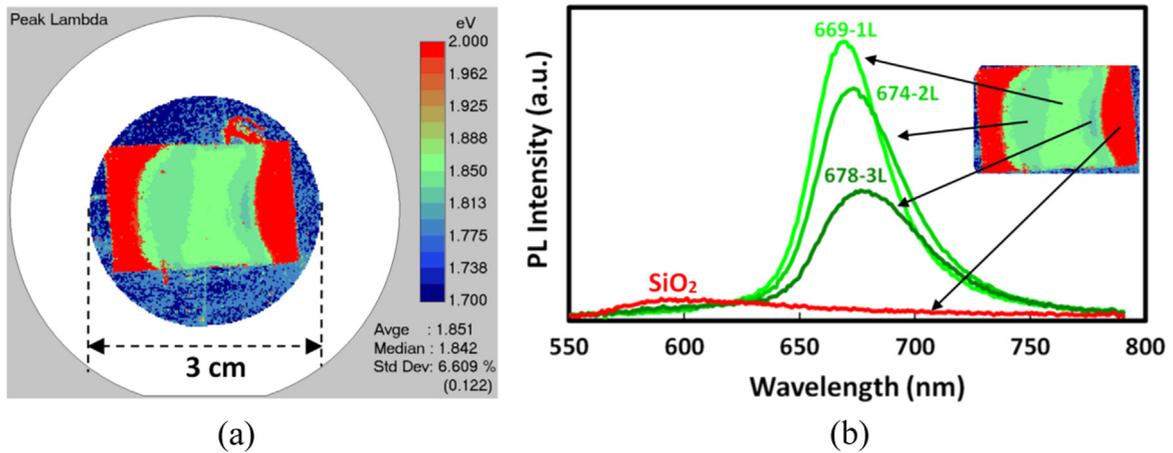


Fig. 3. PL characterization of synthesized MoS₂ films grown on a SiO₂/Si substrate. (a) PL mapping with a scanning spatial resolution of 200 μm × 200 μm across the substrate. (b) PL spectra from 4 different areas on the substrate showing layer numbers and thickness dependence of the PL intensity.

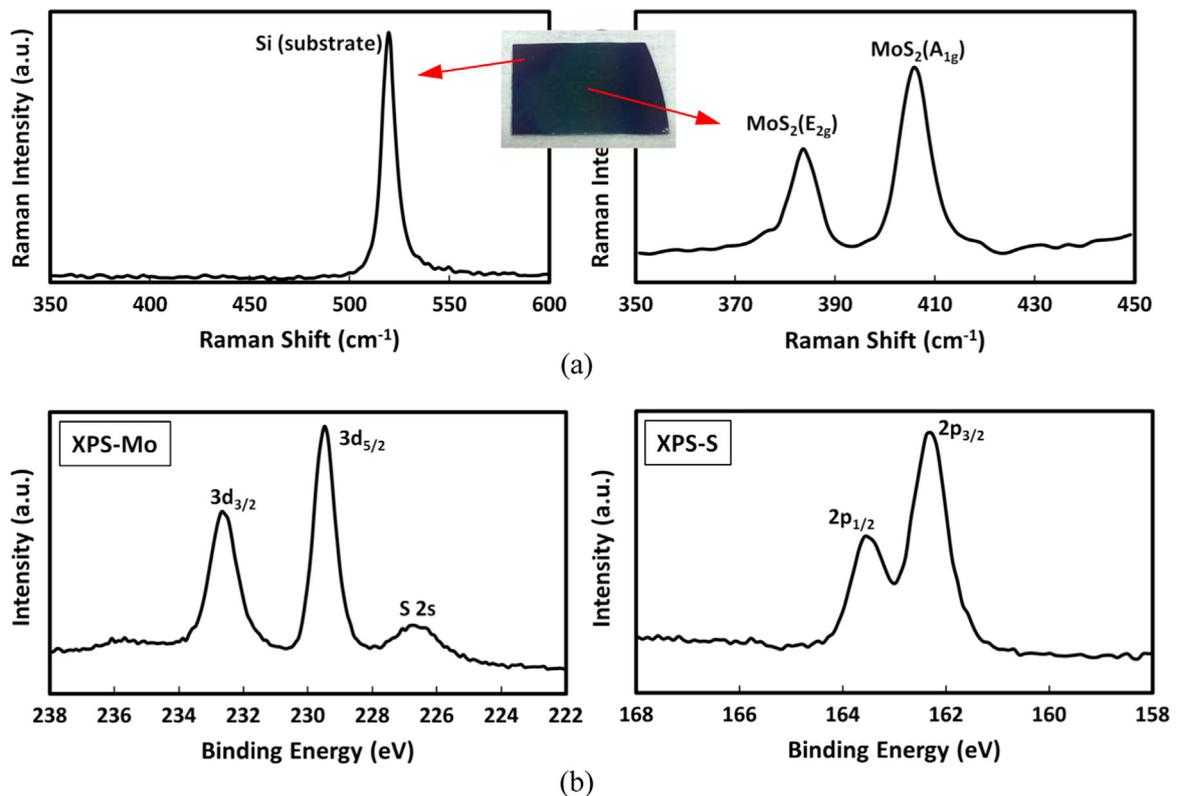


Fig. 4. (a) Raman spectra of Si substrate and synthesized tri-layer MoS₂ on the substrate with two peaks positioned at 383.6 cm⁻¹ and 405.7 cm⁻¹, corresponding to the E_{2g} and A_{1g} vibration modes, respectively. (b) XPS scan of the synthesized MoS₂ film with binding energy of Mo 3d at 229.5 eV and 232.6 eV, and S 2p at 162.3 eV and 163.6 eV.

reported by other publications, for example, [15,16]. With improvement of growth conditions, these crystals now form a continuous form as shown in Fig. 2(d). A scratch was made intentionally for AFM scanning. The height profile of a tri-layer MoS₂ film with a thickness of 2.526 nm is shown in Fig. 2(e). The image also confirms the absence of grain boundary in micrometer scale.

PL was performed by a commercial room temperature PL mapping system, VerteX from Nanometrics, Inc., to characterize and confirm the synthesized MoS₂ atomic layers. A diode-pumped solid-state laser (532 nm, 50 mW) was applied as the excitation source to scan an area of 3 cm-diameter which covers the whole SiO₂/Si substrate, with a scanning spatial resolution of 200 μm × 200 μm. The mapping of λ_{peak} across the whole substrate is shown in Fig. 3(a) using the software equipped in the VerteX system. Typical PL spectra collected from 4 different areas (different

colors as in Fig. 3(a)) on the SiO₂/Si substrate are illustrated in Fig. 3 (b) with signal intensity normalized. These peaks in the PL spectra are around ~670 nm (1.85 eV), which is correlated to the A direct excitonic transition of MoS₂. It can be also seen that the PL spectrum of the monolayer MoS₂ film shows the strongest emission, and the intensity drops for bilayer and tri-layer films. This confirms that the optical property of as-grown MoS₂ films exhibit dependence on layer numbers due to an evolution of the bandgap with the layer no. This result is similar as the exfoliated films and synthesized films reported by other methods [18,20–22]. It is noted that the PL peak corresponding to the B exciton is not clear, which is usually attributed to lattice disorder or residual dopants that decouple the spin–orbital interaction [20,23].

Raman and XPS spectroscopy was applied to further confirm and evaluate the quality of synthesized MoS₂ films. A LabRAM HR

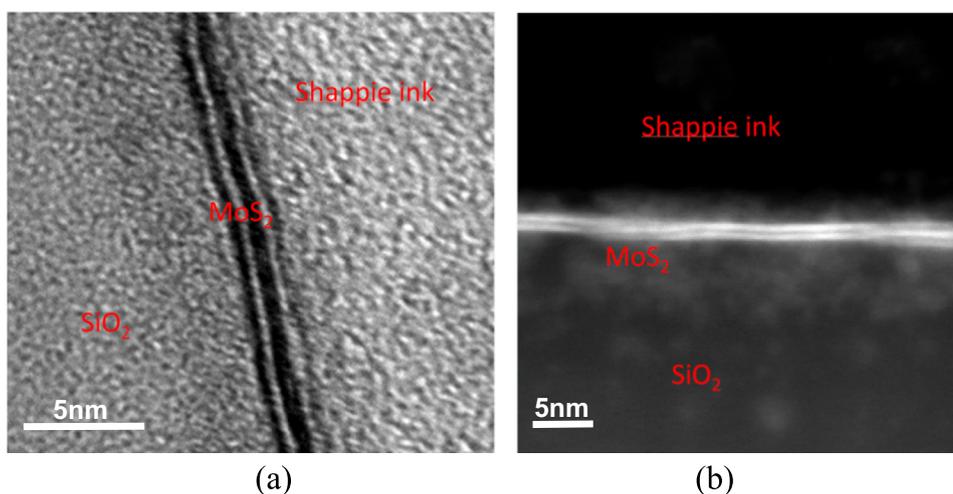


Fig. 5. (a) HREM and (b) STEM Z contrast images show the synthesized monolayer and bilayer MoS₂ films.

Raman confocal microscope by Horiba Scientific was used for measurement. The wavelength of the input laser was 442 nm. Fig. 4(a) shows a representative characteristic in comparison of signals from areas with and without MoS₂ film. The area without MoS₂ only shows the peak of Si substrate which is at 520.6 cm⁻¹. The area with MoS₂ shows two peaks of 383.6 cm⁻¹ and 405.7 cm⁻¹, which correspond to the E_{2g} and A_{1g} vibration modes, respectively. It has been reported that the separation ($\Delta = A_{1g} - E_{2g}$) between these two Raman peaks relates to the no of MoS₂ layers [24]. In this area under test, $\Delta = 22 \text{ cm}^{-1}$, which indicates bilayer [18] MoS₂ crystals in this area. Chemical configuration of the synthesized MoS₂ film was analyzed and confirmed by XPS characterization. Fig. 4(b) shows the XPS spectra of as-grown MoS₂ film for Mo 3d and S 2p. Mo 3d spectra peaks at two binding energies of 229.5 eV and 232.6 eV, which are attributed to 3d_{5/2} and 3d_{3/2} of Mo⁶⁺. S 2p also exhibits two characteristic peak positions at binding energies of 162.3 eV and 163.6 eV, corresponding to spin-orbit 2p_{3/2} and 2p_{1/2}, respectively. All these peak positions are in close agreement with other reported values [15,25], and confirm that the synthesized MoS₂ film have 2h-MoS₂ crystal structure with semiconductor properties [2,26].

HREM and STEM characterizations were applied to further elucidate the MoS₂ film and layer numbers. Regular TEM cross-section samples were prepared with a FEI Strata 237 FIB. Prior to FIB milling, a thin layer of Shappie was applied to specimen surface to prevent ion beam damage. HREM and STEM Z contrast images were taken in a FEI TECNAI F20 supertwin TEM with a Fischione high angle annular dark field detector (HAADF). Some representative images are displayed in Fig. 5. As observed in Fig. 5 (a), bilayer MoS₂ film is shown in this local area, which is consistent with the STEM Z contrast image in Fig. 5(b) by the two bright lines. These layer numbers are in agreement with the results from our AFM, Raman and PL measurements. Such clear two-layer structure also confirms the crystalline nature of the as-grown MoS₂ material.

4. Summary

In this paper we presented preparation of high quality and large area MoS₂ at crystals by CVD process. Monolayer and few-layered MoS₂ films were synthesized on a centimeter-sized SiO₂/Si

substrate. The size and uniformity of the films, the thickness and layer numbers, crystal quality, optical property and chemical configurations were characterized by a variety of techniques. The results confirm that it is promising to grow wafer scale MoS₂ film to realize its applications in electronics.

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